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#### (57) Abstract

Pressure sensitive and hot melt adhesive compositions having improved shear adhesion failure temperatures (SAFT) comprising: (a) a block copolymer having at least two monoalkenyl arene polymer endblocks (A) and at least one elastomeric conjugated-diene midblock (B), said blocks (A) comprising 8-55 % by weight of the block copolymer; (b) about 50 to about 200 phr of a tackifying resin compatible with block (B); and (c) about 5 to about 50 phr of a low molecular weight polyphenylene oxide polymer wherein the molecular weight ( $M_{vis}$ ) of the polyphenylene oxide polymer is from about 1,000 to about 5,000, the  $T_g$  is from about 100° to about 165°C, preferably between 140-163°C.

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## ADHESIVE COMPOSITIONS CONTAINING LOW MOLECULAR WEIGHT POLYPHENEYLENE OXIDES

1	This is a continuation-in-part of copending U.S. Serial No.
2	355,532, filed May 23, 1989, entitled "Adhesive Composition
3	Containing Low Molecular Weight Polyphenylene Oxides," now
4	abandoned.

#### BACKGROUND OF THE INVENTION

#### 1. Field of the Invention

- The invention relates to the use of low molecular weight polyphenylene oxides in adhesive blends comprising styrenic triblock copolymers such as polystyrene-polyisoprene-polystyrene (S-I-S) and polystyrene-polybutadiene-polystyrene (S-B-S) to provide increases in the shear adhesion failure temperatures (SAFT) of the corresponding pressure sensitive, hot melt pressure sensitive or hot melt adhesives. The SAFT increases are obtained without significant hot melt formulation viscosity increases and with little impact on the pressure sensitive adhesives' tack or peel strength.
  - 2. Description of the Prior Art
- In U.S. Patent 3,660,531, there are disclosed polyblends
- 15 containing: (A) greater than 50% of a thermoplastic resin matrix,
- 16 said resin matrix consisting of polyphenylene oxide resin in

1 combination with alkenyl aromatic resins; and (B) less than 50% of an 2 elastomer selected from a group consisting of poly(butadiene), and 3 random, block or graft copolymers of butadiene and styrene. The 4 resulting blends exhibit unexpected thermoplastic properties 5 including improved melt processability and impact resistance without 6 sacrificing the desirable heat distortion temperature and flexural 7 modulus of unmodified polyphenylene oxide resin. The materials in 8 this patent are thermoplastic resins and not adhesives, and the 9 degree of polymerization (DP) of polyphenylene oxide is greater than 10 about 100.

11 Commonly assigned U.S. Patents 3,835,200 and 3,994,856
12 disclose respectively, polyphenylene ether and rubber styrene
13 copolymer compositions containing rigid block copolymers of
14 conjugated dienes and vinyl aromatic compounds, and high impact
15 rubber modified polystyrene compositions containing polyphenylene
16 ether and vinyl aromatic block copolymers; however, the compositions
17 are thermoplastics and the DP of the polyphenylene oxides is greater
18 than 50.

Hot melt adhesive compositions are disclosed in Hansen, U.S. 20 Patent 4,104,323. The adhesive composition is prepared by first melt 21 blending a polyphenylene ether resin and a low molecular weight 22 aromatic resin, and then blending the resulting mixture and a 23 monoalkenyl arene/conjugated diene block copolymer, tackifying resin, 24 and optional hydrocarbon processing oil. The molecular weight of the 25 polyphenylene oxide in the polyphenylene oxide alloy is between 6,000 26 and 25,000. The glass transition temperature is between 170 and 27 205°C. This melt blend avoids the use of solvents while also 28 avoiding oxidative degradation of the block copolymer. The resulting 29 polymer blend possesses a much higher service temperature when used 30 as an adhesive.

An adhesive composition having improved high temperature 32 properties is also disclosed in U.S. Patent 4,141,876. The 33 composition is prepared by melt blending a polyphenylene ether resin, 34 a selectively hydrogenated arene/conjugated diene block copolymer, a 35 tackifying resin, and optionally, a hydrocarbon processing oil. This

patent is restricted to hydrogenated block copolymers which can withstand the extremely high blending temperatures required to disperse the polyphenylene oxide resins, (230°C to 260°C) and to polyphenylene oxide resins having a molecular weight (M<sub>vis</sub>) between 5 6,000 and 25,000. The glass transition temperature of the resin is restricted to between 170° and 210°C.

SUMMARY OF THE INVENTION A need exists in the practice of adhesive formulating to 7 8 obtain adhesive compositions with higher service temperatures and 9 manageable hot melt viscosities. The present invention describes the 10 use of low molecular weight polyphenylene oxide resins (PPO) in hot 11 melt or pressure sensitive adhesive compositions comprising: (a) 100 phr of a block copolymer having at least two 12 13 monoalkenyl arene polymer endblocks A and at least one elastomeric 14 conjugated-diene midblock B, said blocks A comprising 8-55% by weight 15 of the block copolymer. Illustrative of the blocks are styrenic 16 block copolymers such as polystyrene-polybutadiene-polystyrene 17 (S-B-S), polystyrene-polyisoprene-polystyrene (S-I-S), poly 18 ( $\alpha$ -methylstyrene)-polyisoprene-poly ( $\alpha$ -methylstyrene), or their 19 selectively hydrogenated derivatives. (b) about 50-200 phr (part per hundred rubber) of a 20 21 tackifying resin compatible with the rubbery midblock of the block copolymers and (c) about 5-50 phr of a low molecular weight PPO resin with 23 glass transition temperature ( $T_{\alpha}$ ) between 100°C and 165°C, 25 preferably between 140° and 163°C. The tackifying resin, which is compatible with the 26 27 elastomeric midblock of the triblock copolymer, is used to render the 28 formulation tacky. Preferred tackifying resins are those derived 29 from the copolymerization of diolefins and especially of  $C_{\kappa}$  $_{
m 30}$  diolefins such as piperylene with  ${
m C_5}$  olefins such as 31 2-methyl-2-butene. These resins, such as ESCOREZ 1310LC, available 32 commercially from Exxon Chemical, have ring and ball softening points 33 between 80°C to 115°C. Another useful tackifying resin, Zonatac 105

Lite, available from Arizona Chemicals, is prepared by the cationic polymerization of limonene and styrene. Other useful tackifying resins include those derived from rosin esters, terpenes, and terpene 3 phenolic resins. Hydrogenated versions of the above are also useful. 4 Hydrocarbon extending oils (0-200 phr) can be employed in 5 this application to modify the formulation viscosity and to increase 6 the tackiness of the adhesive. The extending oils, referred to as paraffinic/naphthenic oils are fractions of refined petroleum products having less than 30% by weight aromatics and viscosities 10 ranging from 100 to 500 SSU at 100°F. Oils are commercially 11 available such as Shellflex 371, a naphthenic oil manufactured by 12 Shell. 13 The adhesive formulations are prepared by dissolving in a 14 solvent such as toluene, and casting over a substrate such as mylar. 15 Optionally, to apply the formulation as a hot melt, the components 16 are melt blended in a Brabender mixer. The temperature for melt 17 blending will depend upon the  $T_{\sigma}$  of the PPO. This is a significant 18 advantage of using PPO of lower  $T_{\alpha}$  than that claimed in U.S. 19 Patents 4,104,323 and 4,141,876. The invention discovery is that polyphenylene oxide 20 21 copolymers, having low molecular weight and high glass transition 22 temperatures, extend the temperature range of pressure sensitive and 23 hot melt adhesive systems which contain styrenic triblock 24 copolymers. This is a consequence of their compatibilities with the 25 polystyrene domains of the triblock copolymers used in these adhesive 26 applications. Because these adhesive formulations are useful up to 27 the glass transition temperature of the polystyrene domains, blending  $28\,$  a high  $\rm T_{_{\rm C}}$  PPO polymer into the polystyrene domains increases the 29  $T_{\sigma}$  of the glassy domains and consequently increases the useful 30 temperature range of the adhesive. The glass transition temperature 31 range for the PPO resin, 100-165°C, preferably 140-163°C enables hot 32 melt application of the adhesive formulation. Higher Tg PPO resins

33 cannot be hot melt processed unless they are preblended with low

35 U.S. Patent 4,104,323. Furthermore, the lower Tg PPO's of this

34 molecular weight aromatic resins such as polystyrene as described in

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invention provide superior adhesive properties compared with the higher Tg PPO's.

According to the "Glossary of Terms Used in the Pressure
Sensitive Tape Industry", a pressure sensitive adhesive is a material
which is aggressively and permanently tacky, adheres without the need
of more than finger pressure, exerts a strong holding force, and has
sufficient cohesiveness and elasticity that it can be removed from
substrates without leaving a residue. A hot melt adhesive, on the
other hand, is a 100% nonvolatile thermoplastic material that is
heated to a melt and applied to the substrate as a liquid. The hot
melt bond forms after the liquid cools and solidifies. Some pressure
sensitive adhesives, such as those based on block copolymers, are
applied as hot melts, and are referred to as hot melt-pressure
sensitive adhesives.

Typically, commercial PPO's are derived from the 2.6-dimethyl phenol monomer. In accordance with this invention there is described the use of high T<sub>g</sub>, PPO copolymers. One advantage of the use of the copolymers is the lower cost of the monomers such as 0-cresol as compared with the more expensive 2.6-dimethyl phenol monomer thereby resulting in a lower cost PPO. Further, the use of comonomers yields the low molecular weight PPO resins which are best suited for these applications. The useful glass transition temperature range for these PPO resins ranges from 100-165°C, preferably between 140-163°C. This range, less than that described in U.S. Patents 4,104,323 and 4,141,876, provides superior adhesive service temperature increases while allowing hot melt processibility below 200°C.

These low molecular weight polyphenylene oxides improve the high temperature performance of styrenic block copolymers in pressure sensitive adhesive systems. For example, a 7 parts per one hundred rubber (phr) loading of the PPO in a formulation provides about a 32 32°F improvement in the shear adhesion failure temperature (SAFT) with little impact on the pressure sensitive adhesive's tack.

#### DETAILED DESCRIPTION OF THE INVENTION

1 In the use of low molecular weight polyphenylene oxides to 2 increase the service temperatures of block copolymer adhesive 3 systems, the upper use temperature of these adhesives is limited to 4 the softening temperature  $(T_n)$  of the polystyrene domains. In accordance with this invention, a high  $\mathbf{T}_{\sigma}$  PPO with good polystyrene 5 thermodynamic compatibility increases the service temperature when 6 blended into the adhesive formulation. 7 Block copolymers employed in the invention may have 8 geometrical structures, however the invention does not depend on a 9 particular structure, but rather upon the chemical constitution of 10 each of the polymer blocks. Thus, the structures may be linear, 11 12 radial, or branched so long as each copolymer has at least two 13 polymer endblocks and at least one polymer midblock. Thus the invention contemplates (but is not limited to) the use of configurations such as (A-B-A)<sub>n</sub> where n varies from 1 to 20, and 16 preferably from 1 to 3, most preferably 1. Methods for preparation of such polymers are well known in the art. Although the term 18 triblock is used throughout it is to be understood that where applicable the radial and branched blocks are included. 19 20 The invention applies especially to the use of polymers 21 having the configuration of the following typical species: 22 polystyrene-polybutadiene-polystyrene (SBS) 23 polystyrene-polyisoprene-polystyrene (SIS) 24 poly(alpha-methylstyrene)-polybutadiene-poly (alpha-methylstyrene) (aMS-B-aMS) 25 poly(alpha-methylstyrene)-polyisoprene-poly 26 27 (alpha-methylstyrene) ( $\alpha MS-I-\alpha MS$ ). It is to be understood that both Blocks A and B may be 28 29 either homopolymer or random copolymer blocks as long as each block 30 predominates in at least one class of the monomers characterizing the 31 blocks as defined. Thus, blocks A may comprise styrene/alpha-32 methylstyrene copolymer blocks or styrene/butadiene random copolymer 33 blocks as long as the blocks individually predominate in monoalkenyl 34 arenes. The term "monoalkenyl arene" includes styrene and its

1 analogs and homologs including alpha-methylstyrene and

2 ring-substituted styrenes, particularly ring-methylated styrenes.

3 The preferred monoalkenyl arenes are styrene and alpha-methylstyrene,

4 and styrene is particularly preferred. The blocks B may comprise

5 homopolymers of butadiene, isoprene, copolymers of butadiene and

6 isoprene and copolymers of one of these two dienes with monoalkenyl

7 arene as long as the blocks B predominate in conjugated diene units.

8 The rubbery midblock of these polymers may be hydrogenated, but

9 non-hydrogenated midblocks can also be used since excessively high

10 blending temperatures are not generally required to prepare the

11 blends of the present inventory. When the monomer employed is

12 butadiene, it is preferred that between about 35 and about 55 mole

13 percent of the condensed butadiene units in the butadiene polymer

14 block, have a 1,2 configuration.

Polyphenylene oxides of the invention will have repeating to units represented by the formula:

$$\begin{array}{c|c} & & \\ & &$$

nucleus of the next adjoining unit, n is a positive integer of from 19 10 to about 40 thereby providing a MW range of about 1000-5000, and 20 each Q is a monovalent substituent selected from the group consisting 21 of hydrogen, halogen, hydrocarbon radicals, hydrocarbonoxy radicals, 22 and halohydrocarbonoxy radicals having at least two carbon atoms 23 between the halogen atom and phenyl nucleus. Especially preferred 24 polyphenylene oxide resins for purposes of the present invention are 25 those having alkyl substitutions in the two positions ortho to the 26 oxygen ether atom - i.e. where each Q is alkyl, most preferably, 27 having from 1 to 4 carbon atoms.

The polyphenylene oxides employed in accordance with the invention, prepared from 2,6-xylenol and additional comonomers such as o-cresol, allow the cost of the PPO to be materially reduced.

Also, since it is necessary to control the extent of polymerization to obtain PPO products of low molecular weights, the use of the comonomers and control of the amount of oxygen admitted to the reaction allows preparation of the low molecular weights necessary to the invention.

In general, the low molecular weight polyphenylene oxides are prepared using a cuprous chloride-pyridine catalyst system in chlorobenzene solution. Magnesium sulfate is used to remove moisture from the reactions. The products are isolated by precipitation with a 10% HCl/methanol solution, and are dissolved and reprecipitated to remove any residual traces of catalyst or diphenoquinone side products.

PPO yields and glass transition temperatures are controlled by varying the degree of polymerization. This is achieved by changing the reaction time and consequently the amount of oxygen. A longer reaction time permits the formation of higher molecular weight and high T<sub>g</sub> products, which, when precipitated, afford higher recoveries.

Further control of the molecular weight is provided by the 23 use of o-cresol or other comonomers, which give low degrees of 24 polymerization with the present catalyst system.

Polyphenylene oxides of low molecular weight, useful in the invention, also can be prepared according to the Perec article in J. of Polymer Science (vol 25, p 2605) from 4 bromo-2,6-dimethylphenol as monomer (see Example 5).

#### EXAMPLE 1

Cuprous chloride (10g) and pyridine (50ml) are stirred for 30 30 minutes in 500 ml chlorobenzene. o-Cresol (48ml) and anhydrous 31 magnesium sulfate (1.5g) are added and the reaction is stirred for 28 32 hours at room temperature. The insoluble portion of the reaction is 33 filtered away and the resin is precipitated with a 10% HC1/methanol

- 1 solution. The resin is isolated by filtration and washed with
- methanol. The yield is 15g (30%) of a pale orange, brittle solid.
- 3 The glass transition temperature of the solid is 103°C and H-NMR of
- 4 the solid shows a 1:1 ratio of aliphatic to aromatic protons.

#### EXAMPLE 2

Cuprous chloride (10g) and pyridine (50ml) are stirred for 30 minutes at room temperature in 500 ml chlorobenzene. o-Cresol (25g), 2,6-xylenol (25g), and anhydrous magnesium sulfate (1.5g) are added and the reaction is stirred for 28 hours. The insoluble portion of the reaction mixture is removed by filtration and the resin is isolated by precipitation with 10% HCl/methanol. The resin is isolated by filtration and redissolved in toluene and precipitated with methanol to remove any residual catalyst or dimeric side products. The yield is 38g (76%) of a pale orange solid. The glass transition temperature is 105°C and H-NMR analysis shows a 5:3 ratio of aliphatic to aromatic protons.

#### EXAMPLE 3

The procedure of Example 2 is followed except that 26.5g of 2,6-xylenol and 26.5 g of o-cresol are used. The reaction is stirred 18 for 48 hours. A 70% yield of a pale orange solid is obtained. The 19 glass transition temperature of the resin is 153°C and H-NMR analysis 20 shows a 9:5 ratio of aliphatic to aromatic protons.

#### **EXAMPLE 4**

The procedure of Example 1 is followed except that 50g of 22 2,6-xylenol is used instead of the o-cresol. Also, the resin is 23 dissolved in toluene and precipitated with methanol. A 61% yield of 24 a yellow solid is obtained. The glass transition temperature of the 25 solid is 154°C and H-NMR analysis of the solid shows a 3:1 ratio of 26 aliphatic to aromatic protons.

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#### EXAMPLE 5

4-Bromo-2,6-dimethylphenol (38g) is dissolved in 316 ml 6N NaOH. Ammonium hydrogen sulfate (5.08g) and 316 ml toluene are added, and the mixture is stirred for 2 3/4 hours, whereupon, it is quenched with dilute HCl. The toluene phase is separated and dried with magnesium sulfate, and the polymer is isolated by precipitation with methanol (5.5g). DSC and GPC analyses are performed with the following results:  $T_0$ =163°C, Mn=2600, Mw/Mn=1.53.

#### **EXAMPLE 6**

The procedure of Example 3 was followed except that 75g 2, 6-xylenol, 50 mol pyridine, 900 ml chlorobenzene, and 5g magnesium sulfate were used. The mixture was stirred for 72 hours. The polymer yield was 43.5g, and the glass transition temperature was 12 145°C.

In summary, the yields, glass transition temperatures, and product compositions for the PPO products prepared for testing in adhesive formulations are as follows:

		GLASS TRANSITION  TEMPERATURE	YIELD	COMPOSITION
16	Example 1	103°C	30%	o-Cresol
17	Example 2	105°C	76%	3:4 Xylenol:o-Cresol
18	Example 3	153°C	70%	1:1 Xyleno1:o-Creso1
19	Example 4	154°C	61%	Xylenol
20	Example 5	163°C	24%	Xylenol
21	Example 6	145°C	30%	1:1 Xylenol:o-Cresol

PPO product compositions were determined using H-NMR spectroscopy. A ratio of aliphatic protons (1.5-2.5 ppm) to aromatic protons (6-7.4 ppm) indicates the relative amounts of cresol and xylenol present in the resins. An entirely 2,6-xylenol product contains a 3:1 ratio of aliphatic to aromatic protons while an entirely o-cresol product contains a 1:1 ratio of aliphatic to aromatic protons.

In the following embodiments, examples and comparisons, these materials were employed:

- 3 (1) Kraton 1107; a styrene-isoprene-styrene block copolymer from Shell having block molecular weights of about 13,000-160,000-13,000.
- 6 (2) ESCOREZ 1310LC; a C<sub>5</sub> olefin/diolefin tackifying resin from Exxon Chemicals having a ring and ball softening point of 95°C.
- 9 (3) Stereon 840A; a tapered styrene-butadiene-styrene block 10 copolymer from Firestone having Mn of 60,000 and 43 wt % 11 styrene.
- 12 (4) Zonatac 105L; a limonene/styrene tackifying resin from
  13 Arizona Chemicals having a ring and ball softening point of
  14 105°C.
- 15 (5) Shellflex 371; a naphthenic extending oil from Shell.
- 16 (6) Irganox 1010; an antioxidant from CIBA-Geigy.
- 17 (7) Noryl; a PPO from General Electric having a Tg of 194°C.

#### ADHESIVE TESTING WITH SIS FORMULATIONS

S-I-S formulations with E-1310LC as tackifier resin were prepared for testing as pressure sensitive adhesives. All PPO products were used at two different levels and the 90° quick stick, 180° peel, polyken tack, and shear adhesion failure temperatures were measured for each of the formulations. The formulations were cast from toluene onto mylar, and dried in an oven at 80°C to give a .0015 in. coating.

The adhesive tests are those commonly employed by the pressure sensitive adhesive industry. In the shear adhesion failure temperature test, a 1"x1" overlap of tape to a stainless steel substrate is made with a 4.5 pound roller. A 1 kg weight is hung from the tape and the assembly is placed in an oven. The temperature is increased at 40°F/hour and the temperature at which the weight drops is recorded as the SAFT. In the polyken tack test, a steel probe contacts the adhesive tape with a specified force for a 1

- 1 second dwell time. The force required to break the bond between the
- 2 adhesive and the stainless steel probe is measured (g). The 180°
- 3 peel test involves placing a length of tape on a stainless steel
- 4 plate and laminating it with a 1-pound roller. The force (1b/in)
- 5 required to peel the tape at a 180° angle on an Instron is recorded.
- The results of the adhesive testing are summarized in Table

7 1.

TABLE 1

8	<u>1-</u>	4 Contro	1 1	<u>2</u>	3	4	5-8	<u>5</u>	<u>6</u>	7	8	9
							Contro	<u>1</u>				
9	KRATON 110	7 100	100	100	100	100	100	100	100	100	100	100
10	E-1310LC	150	150	150	150	150	150	150	150	150	150	150
11	PPO Ex. 1	-	7.31	4.7	-	-	- "	-	-	-	-	-
12	PPO Ex. 2	-	-	-	7	14	-	•	-	-	-	-
13	PPO Ex. 3	-	-	-	_`	-	-	7	14,	-	-	-
14	PPO Ex. 4	-	-	-	-	-	-	-	-	7	14	-
15	PPO Ex. 5	-	-	-	-	-		-	-	-	-	7
16	Irganox 10	010 .2	2	2	2	2	2	2	2	2	2	2
17	90° Quick											
18	Stick											
19	(lbs/in)	2.3	2.3	2.9	2.6	2.6	1.5	2.7	1.9	1.5	1.1	-
20	180° Peel	to .										i
21	SS (lbs/i	n) 6.4	6.2	6.0	5.9	5.6	4.9	5.1	5.6	4.9	5.3	6.25
22	Polyken T	ack										
23	(g)	1000	702	605	737	350	720	603	495	699	518	1480
24	SAFT											
25	(*F)	200	217	220	225	244	204	234	248	237	244	232

It is apparent from Table 1 that the examples representative
of the invention have superior SAFT than those of the comparative
examples. This indicates that lower T<sub>g</sub> PPO resins are also useful
in increasing the service temperatures of adhesives. Finally, the
tack and peel properties of these adhesives are not adversely
affected by the PPO resins as indicated by maintenance of the peel
and quick stick values with modest declines in polyken tack.
Figure 1 illustrates the adhesive performance findings for
use of the PPO product of Example 3 with SIS formulations.

#### ADHESIVE TESTING WITH SBS FORMULATIONS

Stereon 840 (SBS) formulations with a Zonatac 105 Lite/
Shellflex 371 tackifying system were prepared for testing as hot melt
adhesives. All four PPO products were used at different levels and
the results of the 180° peel and shear adhesion failure temperatures
are compiled in Table 2.

Figure 2 illustrates the superior adhesive performance findings for the use of the PPO product of this invention with SBS formulations.

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1	_		

	1-4 Control	٦I	<b>71</b>	ml	<b>~</b> }	4 5-8 Control	so]	91	<b>~</b> 1	®]	9-12 Control	9 10	#	21
SIEREON 840A	100	100	100	100	100	100	100	100	100	100 100 100 100 100	100	100 100 100 100	100	100
Zonatac 105 Lite	120	120	120	120	120	148	134	120	134 120 134 120	120	140	134 120 134 120	134	120
Shellflex 371	30	30	30	30	30	28	28	28	28	28		•	ı	•
PPO Ex. 1	ı	<b>s</b> n	10	1	ı	ſ	:		1		1	1	1	•
PPO Ex. 2	•	1	•	•	30	1		1	•		1	:	1	ı
PPO Ex. 3	1				1	•	7	28			ı	14 28	ŧ	1
PPO Ex. 4	•	•	t	1	1			ι	14	28	•		14	28
Irganox 1010	7	~	~	~	~	~	1.4	1.4	1.4 1.4 1.4 1.4	1.4	1.4	1.4 1.4	1.4	1.4 1.4 1.4
180° Peel to 53 (1bs/in).	4.2	2.5	2.9	2.6	1.5 4.4	<b>7.</b> 7	3.8	1.8	3.8 1.8 5.8 0.9	6.0	3.2	1.9 1.5 3.0 0.7	9.0	0.7
SAPT (*P)	160	176	184	193	213 165	165	197	214	197 214 203 216	216	170	200 220 216 235	216	235

	TABLE 3:	FORMULAT:	ON VISCOSITY	PROFILE	
		1	<u>2</u>	<u>3</u>	4
1	Kraton 1107	<b>4</b> g	<b>4</b> g	-	-
2	Stereon 840A	-	-	3.6g	3.6g
3	Escorez 1310LC	6 <i>g</i>	<b>6</b> g	-	-
4	Zonatac 105Lite	<b>-</b> ·	-	5.4g	4.3g
5	PPO Ex.3	-	0.6g	-	_
6	PPO Ex. 4	•	-	-	1.0g
7	Shellflex 371	-	-	1.0g	1.0g
8	Viscosity (Ps)				
9	180°C	764	710	146	392
10	200°C	280	302	88	173
11	220°C	120	94.	57	96

The viscosity results indicate that the PPO products of the

13 "invention can be formulated into adhesive formulations for hot

melts without significantly altering the viscosity profile.

Stereon 840 (SBS) formulations with a Zonatac 105 15

16 Lite/Shellflex 371 tackifying system were prepared for testing as

17 hot melt adhesives and solvnet cast pressure sensitive adhesives.

18 For the purpose of comparison of the PPO's of this invention with

19 the PPO's of the prior art, the formulations were prepared with the

20 PPO of Example 6 (Tg=145°C) and NORYL (Tg=194°C). For the hot melt

21 adhesive, viscosity, T-Peel, SAFT and PAFT were evaluated.

22 solvent cast pressure sensitive adhesive, 180° peel and SAFT were

23 evaluated.

24 The T-Peel test was performed according to the procedure

25 of ASTM D01876-72, for both aluminum and polyethylene. The shear

26 adhesion failure temperature (SAFT) was determined as described

- above, except that a 500 g weight was used for a 1" x 1" overlap of
- 2 Kraft paper bonded to Kraft paper. The peel adhesion failure
- 3 temperature (PAFT) utilized the same geometry as the ASTM D-1876-72
- 4 T-Peel test except with a 1" x 1" overlap of Kraft paper bonded to
- 5 Kraft paper. The PAFT evaluation was conducted in an oven with a
- 6 200 g weight attached. The reported temperature was the
- 7 temperature at which the bond failed when the oven was ramped at
- 8 40°F/hour. The 180° peel test was as described above. The results
- 9 of the adhesive testing are summarized in Table 4.
- 10 While the invention has focused on the use of certain
- 11 particular low molecular weight PPO polymers having a  $T_{\sigma}$  of about
- 12 100°C to about 165°C to improve the upper temperature performances
- 13 of styrene block copolymer adhesive systems, it is to be understood
- 14 that a wide range of these polymers are suitable and that the
- 15 compositions can be dictated by economic considerations. For
- 16 example, the data show that cresol copolymers exhibited
- 17 performances comparable to the more expensive xylenol homopolymer.
- 18 Therefore, many monomer combinations based on cresylic acids and
- 19 phenol methylation products can be used without departing from the
- 20 spirit and scope of the use of low molecular weight PPO polymers
- 21 for high temperature applications in pressure sensitive and hot
- 22 melt adhesive systems.

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### TABLE 4: PPO Tg COMPARISON

		Hot Mel	t Adhesive	Solvent (from t	Cast PSA <u>oluene)</u>
		1	2	<u>1</u>	<u>2</u>
1	STEREON 840A	100	100	100	100
2	Zonatac 105 Lit	e 120	120	120	120
3	Shellflex 371	38.6	38.6	38.6	38.6
4 5	PPO Ex. 6 (Tg=145°C)	38.6		38.6	
6 7	NORYL PPO (Tg=194°C)		38.6		38.6
8 9	Brookfield Visc 180°C 2	osity 4,450 c <sub>l</sub>	ps*		·
10	200°C 1	1,500 c	os*		
11	T-Peel (lb/in.)				
12	Al/Al	7.1	*		
13	PE/PE	0.1	*		
14	SAFT (°F)				
15	1" x 1" x 500	g			
16	Kraft/Kraft	200			
17	PAFT (°F)				
18	1" x 1" x 100	g			
19	Kraft/Kraft	212	*		
20	180°Peel (lb/in	)			
21	SS			2.5	0.2
22	SAFT (°F)				
23	1" x 1" x 100	0g		213	97
24	*NORYL PPO immi	scible	up to 220°C		

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resins taught in the prior art.

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The most remarkable feature of the data presented in Table 4 is that the NORYL (tg=194°C) could not be hot melt blended at temperatures up to 220°C, in contrast to the low Tg (145°C) PPO of example 6. Furthermore, the adhesive properties of the lower Tg PPO of Example 6 formulations are superior to properties achieved with the higher Tg NORYL resin formulations. These data demonstrate a clear advantage in processability and in adhesive performance for the low Tg PPO compositions of this invention versus the higher Tg PPO

#### CLAIMS:

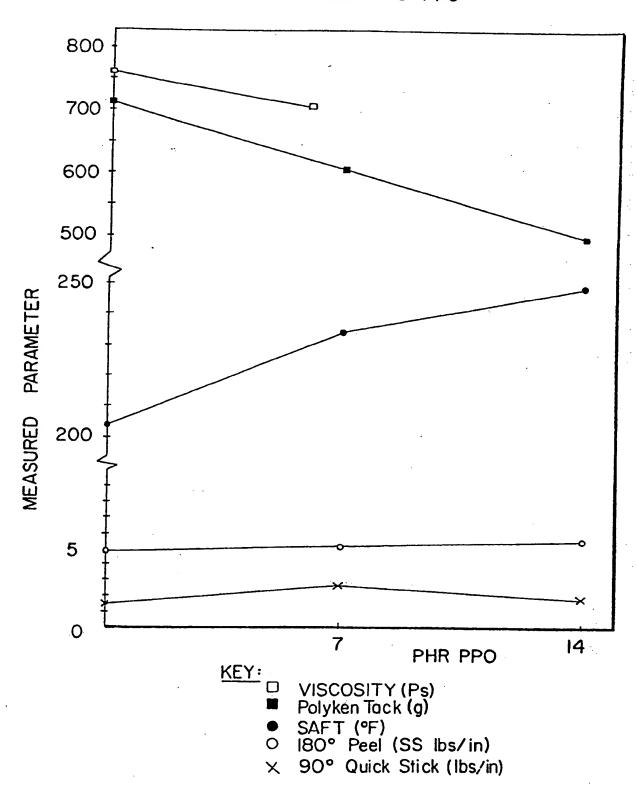
- 1. An adhesive composition having improved shear adhesion failure temperatures (SAFT) comprising:
- (a) 100 phr of a block copolymer having at least two monoalkenyl arene polymer endblocks A and at least one elastomeric conjugated-diene midblock B, said blocks A comprising 8-55% by weight of the block copolymer;
- (b) about 50 to about 200 phr of a tackifying resin compatible with block B; and
- (c) about 5 to about 50 phr of a low molecular weight polyphenylene oxide polymer, having a molecular weight ( $M_{vis}$ ) between about 1000 and about 5,000, and a  $T_q$  of about 100°-165°C.
- 2. The composition of claim 1 wherein the block polymer is a triblock.
- 3. The composition of claim 1, wherein the polyphenylene oxide polymer has a Tg of about 140°-163°C.
- 4. The composition of claim 2, wherein the triblock copolymer comprises styrene endblocks and a polyisoprene rubbery midblock.
- 5. The composition of claim 2, wherein the triblock copolymer comprises styrene endblocks and a butadiene rubbery midblock.
- 6. The composition of claim 1, wherein the block copolymer is a triblock copolymer having styrene-alpha-methylstyrene endblocks and a polyisoprene rubbery midblock.
- 7. The composition of claim 3, wherein the block copolymer is a triblock copolymer having styrene endblocks and a polyisoprene rubbery midblock.

5

- 8. The composition of claim 3, wherein the block copolymer is a triblock copolymer having styrene endblocks and a butadiene rubbery midblock.
- 9. The composition of claim 3, wherein the block copolymer is a triblock copolymer having styrene-alpha-methylstyrene endblocks and a polyisoprene rubbery midblock.
- 10. An adhesive tape comprising the adhesive composition of claim 1.
- 11. A substrate coated with the adhesive composition of claim 1.
- 12. The composition of claim 4, wherein the block copolymer is hydrogenated.
- 13. The composition of claim 7, wherein the block copolymer is hydrogenated.
- 14. The substrate of claim 12, wherein the substrate is metallic.
- 15. A hot melt adhesive comprising the composition of claim
  1.
- 16. A pressure sensitive adhesive comprising the composition of claim 1.
- 17. A hot melt pressure sensitive adhesive comprising the composition of claim 1.

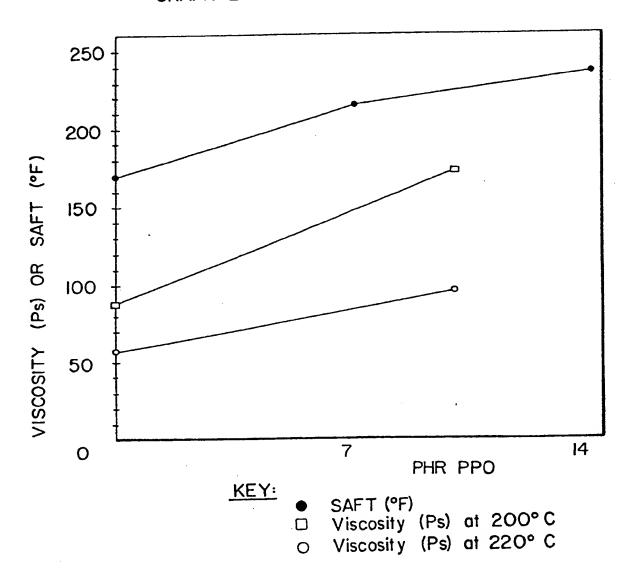
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GRAPH I: SIS/ EXAMPLE 3 PPO



# Hig;Z

GRAPH: 2 SBS/EXAMPLE 3PPO



## INTERNATIONAL SEARCH REPORT

International Application No PCT/US 90/02948

I. CLAS	SIFICATIO	N OF SUBJECT MATTER (it several clas	sification symbols apply, indicate all) 6	
According	g to internat	ional Patent Classification (IPC) or to both No	ational Classification and IPC	
IPC <sup>5</sup> :		9 J 153/02		
II. FIELD	5 SEARCI	1ED		
		Minimum Docum	entation Searched 7	
Classificati	on System		Classification Symbols	<del></del>
IPC <sup>5</sup>		C 09 J, C 08 L		
		Documentation Searched other to the Extent that such Document	than Minimum Documentation	
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III. DOCL	MENTS C	ONSIDERED TO BE RELEVANT		
Category *		on of Document, 11 with indication, where ap	propriate, of the relevant passages 12	Relevant to Claim No. 13
			· · · · · · · · · · · · · · · · · · ·	
У		A, 0001306 (SHELL) 4 April 1979 see claims		1-17
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"A" docucons "E" earli filing "L" documbic citat "O" docu othe "P" docu	rment definitioned to be or document; date iment which is cited to ion or other rment referring ment publishment p	of cited documents: 19 ng the general state of the art which is not a of particular relevance. It but published on or after the international may throw doubts on priority claim(s) or o establish the publication date of another special reason (as specified) ing to an oral disclosure, use, exhibition or hed prior to the international filling date but ority date claimed	"T" later document published after the or priority date and not in conflicted to understand the principle invention.  "X" document of particular relevance cannot be considered novel or involve an inventive step.  "Y" document of particular relevance cannot be considered to involve a document is combined with one ments, such combination being of in the art.  "A" document member of the same p	e; the claimed invention cannot be considered to e; the claimed invention cannot be considered to e; the claimed invention in inventive step when the or more other such docubulous to a person skilled
Date of the	Actual Con	spletion of the International Search	Date of Mailing of this International Sec	irch Report
11th :	Septen	ber 1990	/ 11.10	
Internations	Searching	Authority	Signature of Authorized Officer	<i>'</i>
	EUROPE	AN PATENT OFFICE	//////////////////////////////////////	Weinberg

# ANNEX TO THE INTERNATIONAL SEARCH REPORT ON INTERNATIONAL PATENT APPLICATION NO.

US 9002948 SA 37881

This annex lists the patent family members relating to the patent documents cited in the above-mentioned international search report. The members are as contained in the European Patent Office EDP file on 02/10/90

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